

# SN54ABT2952A, SN74ABT2952A OCTAL BUS TRANSCEIVERS AND REGISTERS WITH 3-STATE OUTPUTS

SCBS203D – AUGUST 1992 – REVISED JANUARY 1998

- State-of-the-Art *EPIC-II<sup>B</sup>*™ BiCMOS Design Significantly Reduces Power Dissipation
- Two 8-Bit Back-to-Back Registers Store Data Flowing in Both Directions
- Noninverting Outputs
- Typical  $V_{OLP}$  (Output Ground Bounce) < 1 V at  $V_{CC} = 5$  V,  $T_A = 25^\circ\text{C}$
- Latch-Up Performance Exceeds 500 mA Per JESD 17
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model ( $C = 200$  pF,  $R = 0$ )
- Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK), Ceramic Flat (W) Package, and Plastic (NT) and Ceramic (JT) DIPs

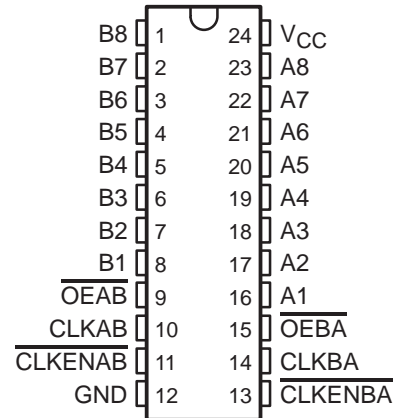
## description

The 'ABT2952A transceivers consist of two 8-bit back-to-back registers that store data flowing in both directions between two bidirectional buses. Data on the A or B bus is stored in the registers on the low-to-high transition of the clock (CLKAB or CLKBA) input provided that the clock-enable (CLKENAB or CLKENBA) input is low. Taking the output-enable ( $\overline{OEAB}$  or  $\overline{OEBA}$ ) input low accesses the data on either port.

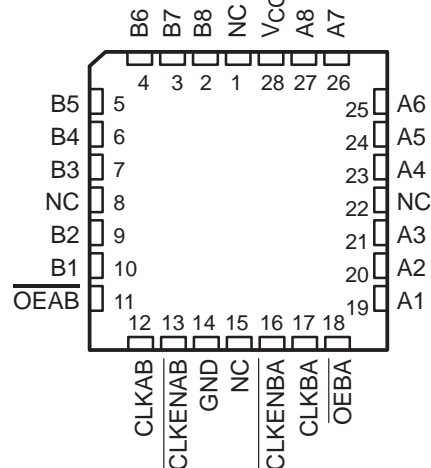
To ensure the high-impedance state during power up or power down,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABT2952A is characterized for operation over the full military temperature range of  $-55^\circ\text{C}$  to  $125^\circ\text{C}$ . The SN74ABT2952A is characterized for operation from  $-40^\circ\text{C}$  to  $85^\circ\text{C}$ .

SN54ABT2952A . . . JT OR W PACKAGE  
SN74ABT2952A . . . DB, DW, PW, OR NT PACKAGE  
(TOP VIEW)



SN54ABT2952A . . . FK PACKAGE  
(TOP VIEW)



NC – No internal connection



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

 **TEXAS  
INSTRUMENTS**

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On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

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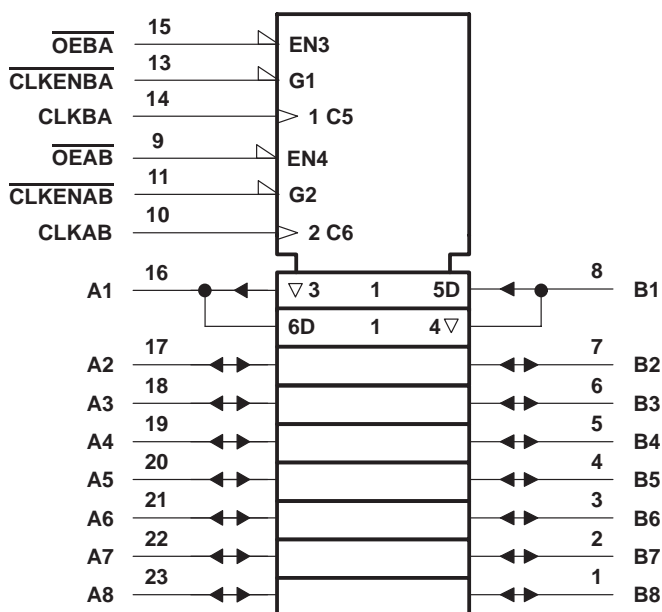
FUNCTION TABLE†

INPUTS				OUTPUT
CLKENAB	CLKAB	OEAB	A	B
H	X	L	X	B <sub>0</sub> ‡
X	H or L	L	X	B <sub>0</sub> ‡
L	↑	L	L	L
L	↑	L	H	H
X	X	H	X	Z

† A-to-B data flow is shown; B-to-A data flow is similar, but uses  $\overline{\text{CLKENBA}}$ , CLKBA, and  $\overline{\text{OEBA}}$ .

‡ Level of B before the indicated steady-state input conditions were established

## logic symbols§

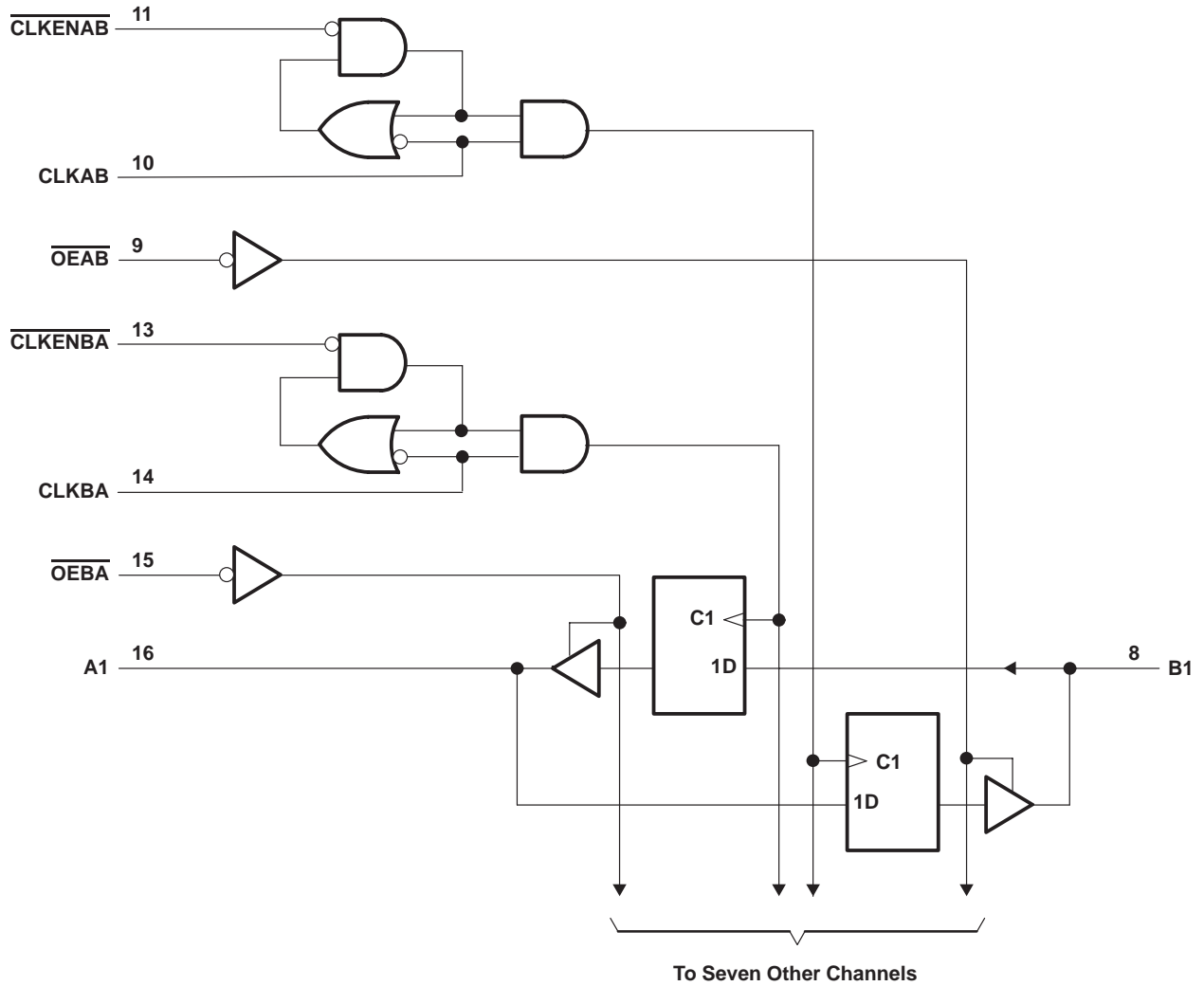


§ This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the DB, DW, JT, NT, PW, and W packages.

SN54ABT2952A, SN74ABT2952A  
 OCTAL BUS TRANSCEIVERS AND REGISTERS  
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logic diagram (positive logic)



Pin numbers shown are for the DB, DW, JT, NT, PW, and W packages.

# SN54ABT2952A, SN74ABT2952A OCTAL BUS TRANSCEIVERS AND REGISTERS WITH 3-STATE OUTPUTS

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## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, $V_{CC}$ .....	-0.5 V to 7 V
Input voltage range, $V_I$ (except I/O ports) (see Note 1) .....	-0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, $V_O$ .....	-0.5 V to 5.5 V
Current into any output in the low state, $I_O$ : SN54ABT2952A .....	96 mA
SN74ABT2952A .....	128 mA
Input clamp current, $I_{IK}$ ( $V_I < 0$ ) .....	-18 mA
Output clamp current, $I_{OK}$ ( $V_O < 0$ ) .....	-50 mA
Package thermal impedance, $\theta_{JA}$ (see Note 2): DB package .....	104°C/W
DW package .....	81°C/W
NT package .....	67°C/W
PW package .....	120°C/W
Storage temperature range, $T_{stg}$ .....	-65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.  
2. The package thermal impedance is calculated in accordance with JESD 51, except for through-hole packages, which use a trace length of zero.

## recommended operating conditions (see Note 3)

		SN54ABT2952A		SN74ABT2952A		UNIT
		MIN	MAX	MIN	MAX	
$V_{CC}$	Supply voltage	4.5	5.5	4.5	5.5	V
$V_{IH}$	High-level input voltage	2		2		V
$V_{IL}$	Low-level input voltage		0.8		0.8	V
$V_I$	Input voltage	0	$V_{CC}$	0	$V_{CC}$	V
$I_{OH}$	High-level output current		-24		-32	mA
$I_{OL}$	Low-level output current		48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		10	10	ns/V
$T_A$	Operating free-air temperature	-55	125	-40	85	°C

NOTE 3: All unused inputs of the device must be held at  $V_{CC}$  or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.



# SN54ABT2952A, SN74ABT2952A OCTAL BUS TRANSCEIVERS AND REGISTERS WITH 3-STATE OUTPUTS

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**electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)**

PARAMETER	TEST CONDITIONS	T <sub>A</sub> = 25°C			SN54ABT2952A		SN74ABT2952A		UNIT
		MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V <sub>IK</sub>	V <sub>CC</sub> = 4.5 V, I <sub>I</sub> = -18 mA			-1.2		-1.2		-1.2	V
V <sub>OH</sub>	V <sub>CC</sub> = 4.5 V, I <sub>OH</sub> = -3 mA	2.5			2.5			2.5	V
	V <sub>CC</sub> = 5 V, I <sub>OH</sub> = -3 mA	3			3			3	
	V <sub>CC</sub> = 4.5 V, I <sub>OH</sub> = -24 mA	2			2				
V <sub>OL</sub>	V <sub>CC</sub> = 4.5 V, I <sub>OL</sub> = 48 mA			0.55		0.55			V
				0.55*				0.55	
V <sub>hys</sub>			100						mV
I <sub>I</sub>	Control inputs	V <sub>CC</sub> = 5.5 V, V <sub>I</sub> = V <sub>CC</sub> or GND		±1		±1		±1	μA
	A or B ports			±100		±100		±100	
I <sub>OZH</sub> ‡	V <sub>CC</sub> = 5.5 V, V <sub>O</sub> = 2.7 V			50*		10		50	μA
I <sub>OZL</sub> ‡	V <sub>CC</sub> = 5.5 V, V <sub>O</sub> = 0.5 V			-50*		-10		-50	μA
I <sub>off</sub>	V <sub>CC</sub> = 0, V <sub>I</sub> or V <sub>O</sub> ≤ 4.5 V			±100*				±100	μA
I <sub>CEX</sub>	V <sub>CC</sub> = 5.5 V, V <sub>O</sub> = 5.5 V, Outputs high			50		50		50	μA
I <sub>O</sub> §	V <sub>CC</sub> = 5.5 V, V <sub>O</sub> = 2.5 V	-50	-100	-180	-50	-180	-50	-180	mA
I <sub>CC</sub>	A or B ports, V <sub>CC</sub> = 5.5 V, I <sub>O</sub> = 0, V <sub>I</sub> = V <sub>CC</sub> or GND	Outputs high		1	250	250	250	250	μA
		Outputs low		24	35	35	35	35	mA
		Outputs disabled		0.5	250	250	250	250	μA
ΔI <sub>CC</sub> ¶	V <sub>CC</sub> = 5.5 V, One input at 3.4 V, Other inputs at V <sub>CC</sub> or GND			1.5		1.5		1.5	mA
C <sub>i</sub>	Control inputs, V <sub>I</sub> = 2.5 V or 0.5 V			3.5					pF
C <sub>io</sub>	A or B ports, V <sub>O</sub> = 2.5 V or 0.5 V			7.5					pF

\* On products compliant to MIL-PRF-38535, this parameter does not apply.

† All typical values are at V<sub>CC</sub> = 5 V.

‡ The parameters I<sub>OZH</sub> and I<sub>OZL</sub> include the input leakage current.

§ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

¶ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V<sub>CC</sub> or GND.

**timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)**

		V <sub>CC</sub> = 5 V, T <sub>A</sub> = 25°C		SN54ABT2952A		SN74ABT2952A		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
f <sub>clock</sub>	Clock frequency	0	150	0	150	0	150	MHz
t <sub>w</sub>	Pulse duration, CLK high or low	3.3		3.3		3.3		ns
t <sub>su</sub>	Setup time before CLK↑	A or B	High or low	2.5		3		ns
		CLKEN		3		3		
t <sub>h</sub>	Hold time after CLK↑	A or B		1.5		1.5		ns
		CLKEN		2		2		



**SN54ABT2952A, SN74ABT2952A**  
**OCTAL BUS TRANSCEIVERS AND REGISTERS**  
**WITH 3-STATE OUTPUTS**

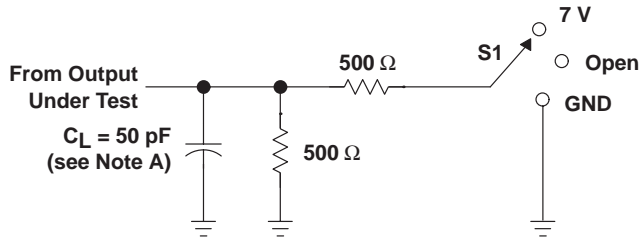
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switching characteristics over recommended ranges of supply voltage and operating free-air temperature,  $C_L = 50$  pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 5$ V, $T_A = 25^\circ$ C			SN54ABT2952A		SN74ABT2952A		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
$f_{max}$			150			150		150		MHz
$t_{PLH}$	CLKAB or CLKBA	B or A	2	3.3	5.2	2	6.3	2	5.9	ns
$t_{PHL}$			2.5	4	6.1	2.5	6.8	2.5	6.3	
$t_{PZH}$	$\overline{OEBA}$ or $\overline{OEAB}$	A or B	1.5	3.2	4.7	1.5	5.7	1.5	5.6	ns
$t_{PZL}$			2	3.7	5.7	2	6.7	2	6.6	
$t_{PHZ}$	$\overline{OEBA}$ or $\overline{OEAB}$	A or B	1.5	3.5	5.1	1.5	6.5	1.5	6.4	ns
$t_{PLZ}$			1.5	3.4	5.9	1.5	6.7	1.5	6.2	

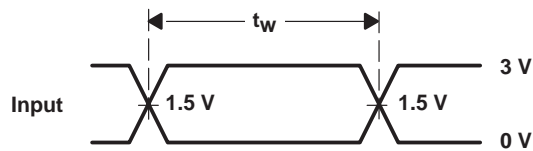


PARAMETER MEASUREMENT INFORMATION

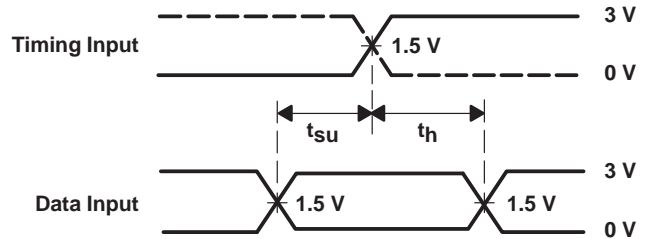


TEST	S1
$t_{PLH}/t_{PHL}$	Open
$t_{PLZ}/t_{PZL}$	7 V
$t_{PHZ}/t_{PZH}$	Open

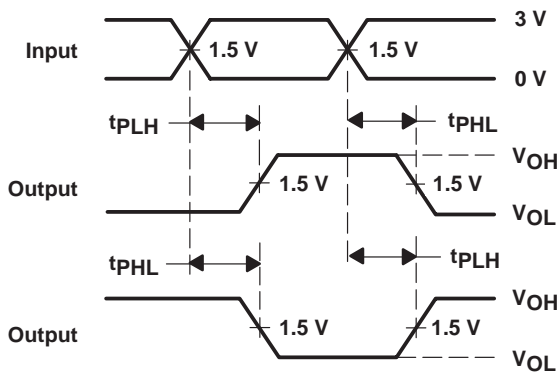
LOAD CIRCUIT



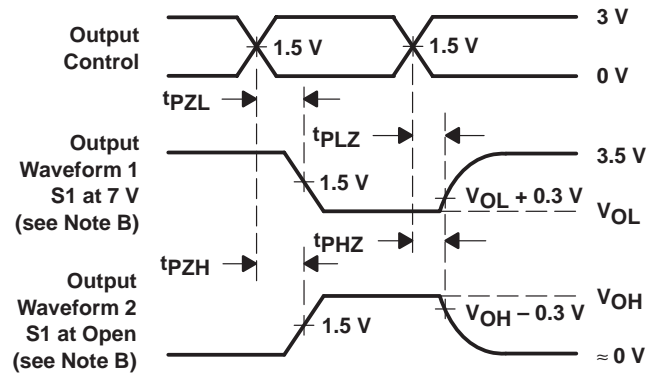
VOLTAGE WAVEFORMS  
 PULSE DURATION



VOLTAGE WAVEFORMS  
 SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS  
 PROPAGATION DELAY TIMES  
 INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS  
 ENABLE AND DISABLE TIMES  
 LOW- AND HIGH-LEVEL ENABLING

- NOTES: A.  $C_L$  includes probe and jig capacitance.  
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.  
 C. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 10 \text{ MHz}$ ,  $Z_O = 50 \Omega$ ,  $t_r \leq 2.5 \text{ ns}$ ,  $t_f \leq 2.5 \text{ ns}$ .  
 D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
5962-9308602Q3A	ACTIVE	LCCC	FK	28	1	TBD	POST-PLATE	N / A for Pkg Type
5962-9308602QKA	ACTIVE	CFP	W	24	1	TBD	A42	N / A for Pkg Type
5962-9308602QLA	ACTIVE	CDIP	JT	24	1	TBD	A42	N / A for Pkg Type
SN74ABT2952ADBLE	OBSOLETE	SSOP	DB	24		TBD	Call TI	Call TI
SN74ABT2952ADBR	ACTIVE	SSOP	DB	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT2952ADBRE4	ACTIVE	SSOP	DB	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT2952ADBRG4	ACTIVE	SSOP	DB	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT2952ADW	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT2952ADWE4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT2952ADWG4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT2952ADWR	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT2952ADWRE4	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT2952ADWRG4	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT2952ANSR	ACTIVE	SO	NS	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT2952ANSRE4	ACTIVE	SO	NS	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT2952ANSRG4	ACTIVE	SO	NS	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT2952ANT	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74ABT2952ANTE4	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SNJ54ABT2952AFK	ACTIVE	LCCC	FK	28	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54ABT2952AJT	ACTIVE	CDIP	JT	24	1	TBD	A42	N / A for Pkg Type
SNJ54ABT2952AW	ACTIVE	CFP	W	24	1	TBD	A42	N / A for Pkg Type

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and



package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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**TAPE AND REEL INFORMATION**



**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ABT2952ADBR	SSOP	DB	24	2000	330.0	16.4	8.2	8.8	2.5	12.0	16.0	Q1
SN74ABT2952ADWR	SOIC	DW	24	2000	330.0	24.4	10.75	15.7	2.7	12.0	24.0	Q1
SN74ABT2952ANSR	SO	NS	24	2000	330.0	24.4	8.2	15.4	2.5	12.0	24.0	Q1

**TAPE AND REEL BOX DIMENSIONS**



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ABT2952ADBR	SSOP	DB	24	2000	346.0	346.0	33.0
SN74ABT2952ADWR	SOIC	DW	24	2000	346.0	346.0	41.0
SN74ABT2952ANSR	SO	NS	24	2000	346.0	346.0	41.0

JT (R-GDIP-T\*\*)

CERAMIC DUAL-IN-LINE

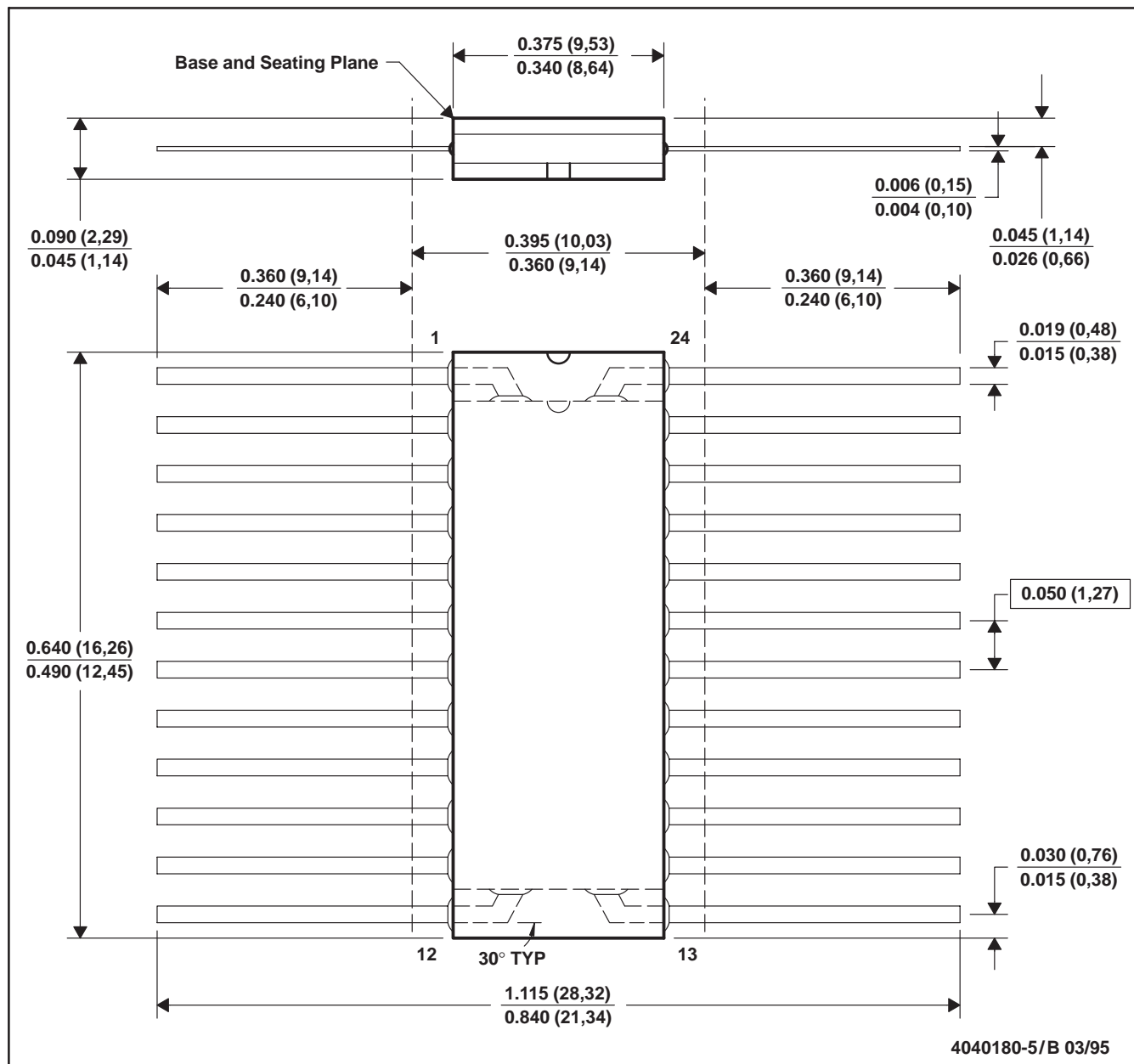
24 LEADS SHOWN



- NOTES: A. All linear dimensions are in inches (millimeters).  
 B. This drawing is subject to change without notice.  
 C. This package can be hermetically sealed with a ceramic lid using glass frit.  
 D. Index point is provided on cap for terminal identification.  
 E. Falls within MIL STD 1835 GDIP3-T24, GDIP4-T28, and JEDEC MO-058 AA, MO-058 AB

W (R-GDFP-F24)

CERAMIC DUAL FLATPACK



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package can be hermetically sealed with a ceramic lid using glass frit.
  - D. Falls within MIL-STD-1835 GDFP2-F24 and JEDEC MO-070AD
  - E. Index point is provided on cap for terminal identification only.

FK (S-CQCC-N\*\*)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.740 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)



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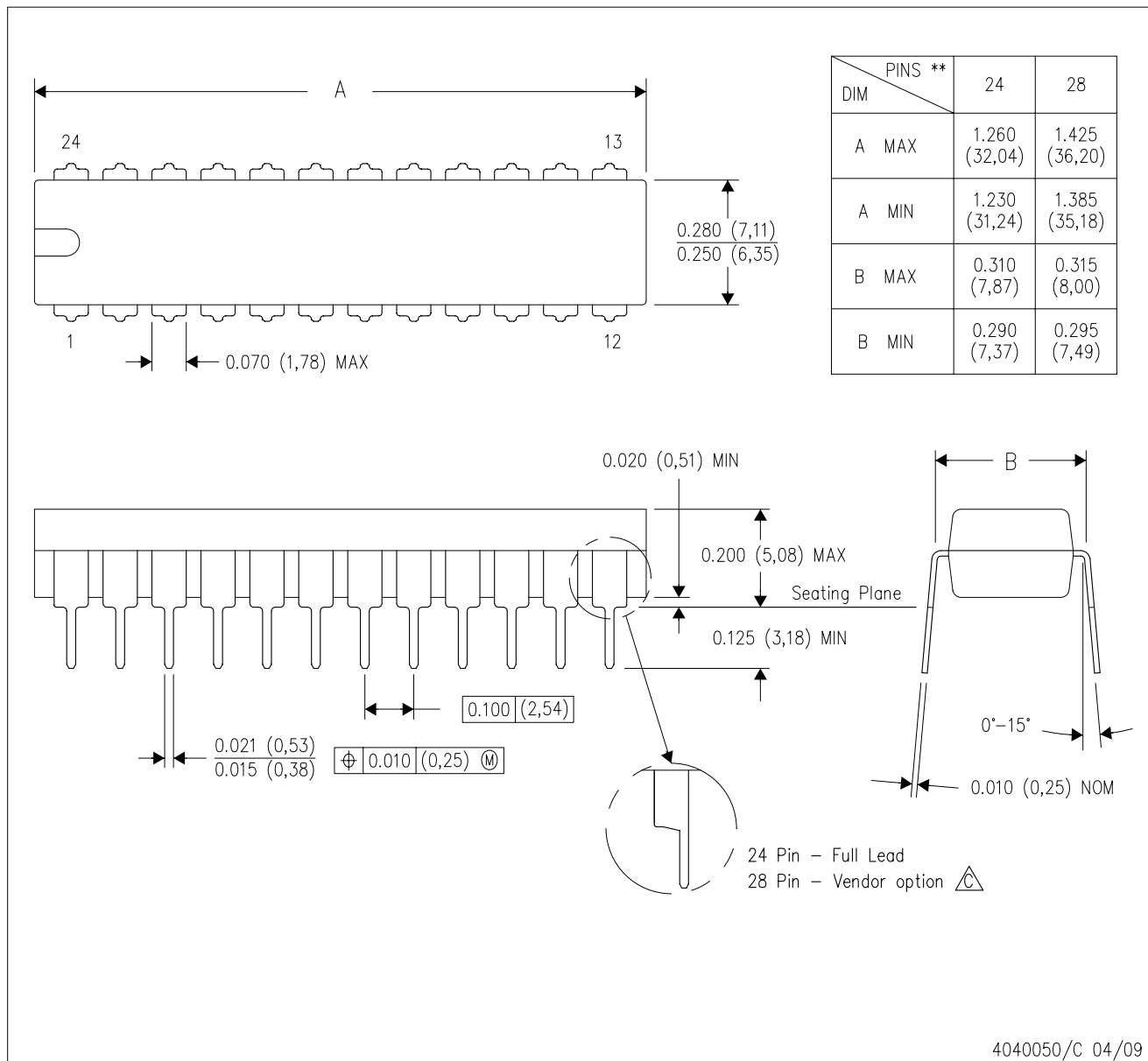
- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - This package can be hermetically sealed with a metal lid.
  - Falls within JEDEC MS-004


# MECHANICAL DATA

NT (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

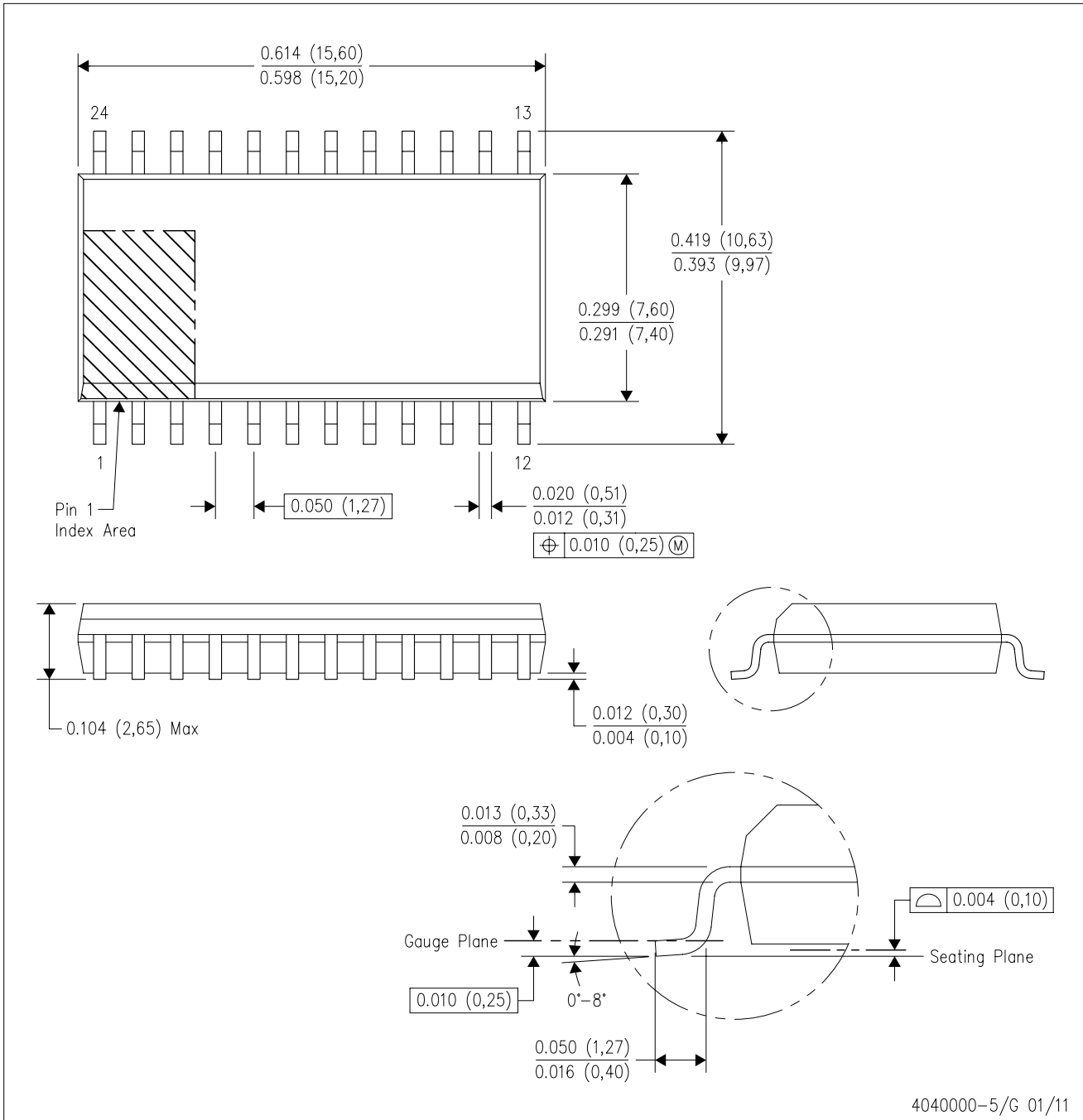
24 PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  -  The 28 pin end lead shoulder width is a vendor option, either half or full width.

DW (R-PDSO-G24)

PLASTIC SMALL OUTLINE

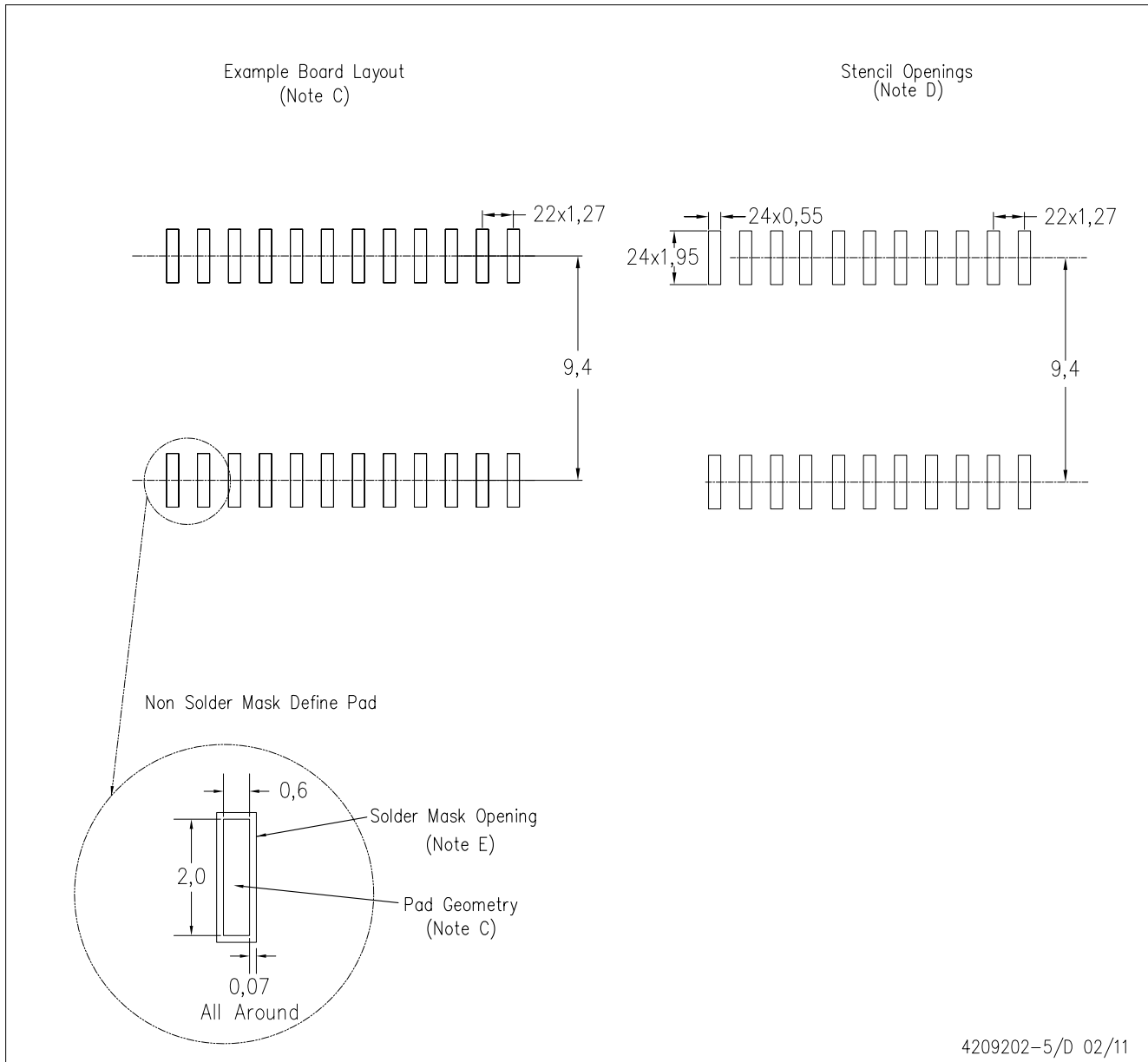


- NOTES:
- A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
  - D. Falls within JEDEC MS-013 variation AD.



DW (R-PDSO-G24)

PLASTIC SMALL OUTLINE



4209202-5/D 02/11

- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Refer to IPC7351 for alternate board design.
  - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525
  - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

# MECHANICAL DATA

NS (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN

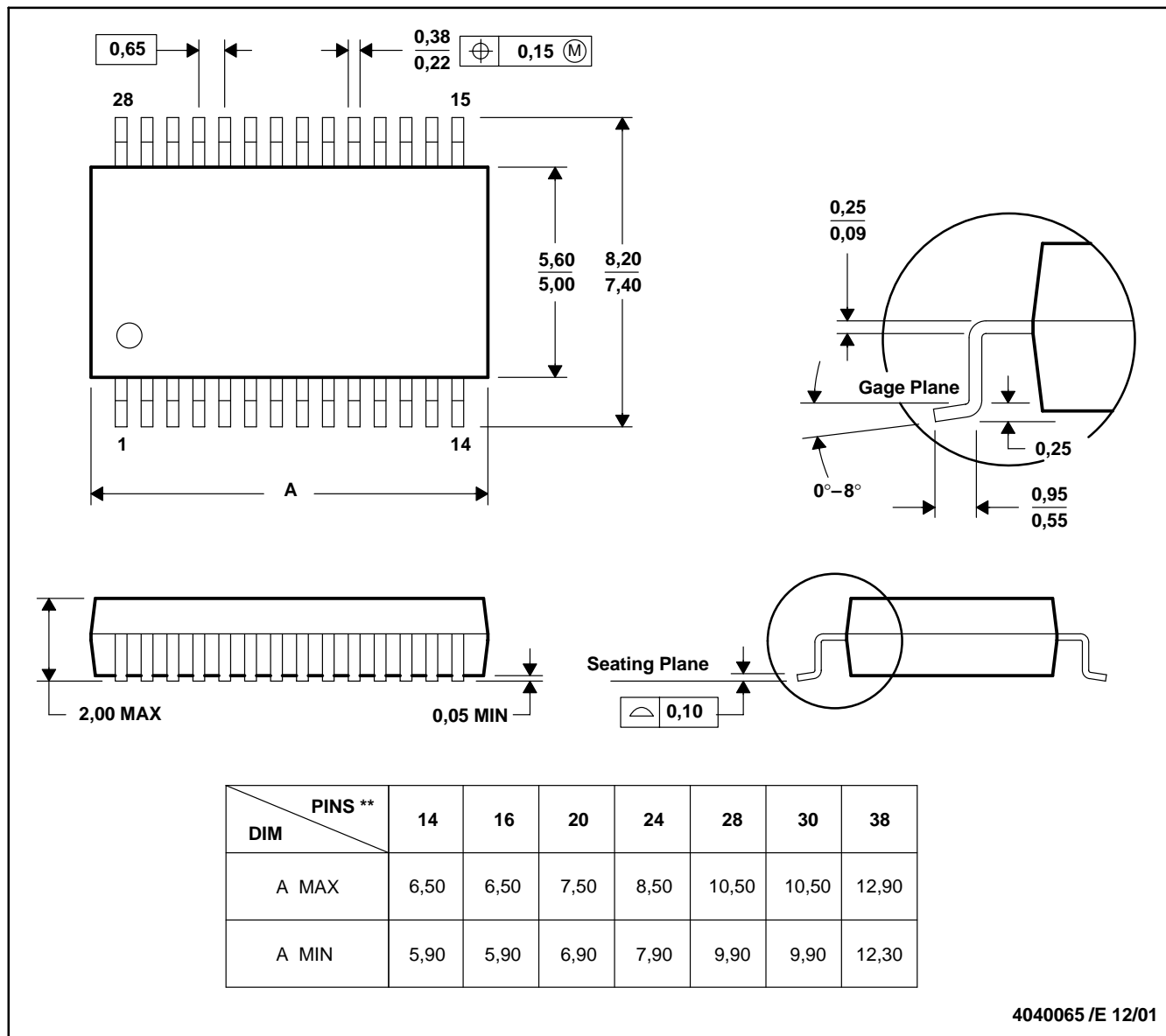


- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

DB (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.  
 D. Falls within JEDEC MO-150

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